



GP
ELECTRONICS

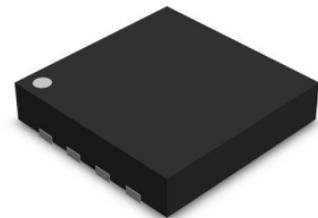
GPAE1204

12V Dual N-Channel MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
12V	3.1mΩ@4.5V	20A
	3.2mΩ@4V	
	3.3mΩ@3.8V	
	3.5mΩ@3.1V	
	3.9mΩ@2.5V	

DFN3*3-8L



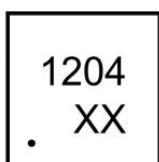
Feature

- Trench Technology Power MOSFET
- Low $R_{DS(ON)}$
- Low Gate Charge
- ESD Protected

Application

- Load Switch
- DC/DC Converter

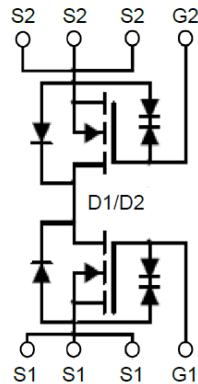
MARKING:



1204= Device Code

XX = Date Code

Schematic diagram



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	12	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current ^{1,4}	I_D	20	A
Pulsed Drain Current ²	I_{DM}	80	A
Power Dissipation ⁴	P_D	3	W
Thermal Resistance from Junction to Ambient ⁵	$R_{\theta JA}$	42	°C/W
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55~+150	°C

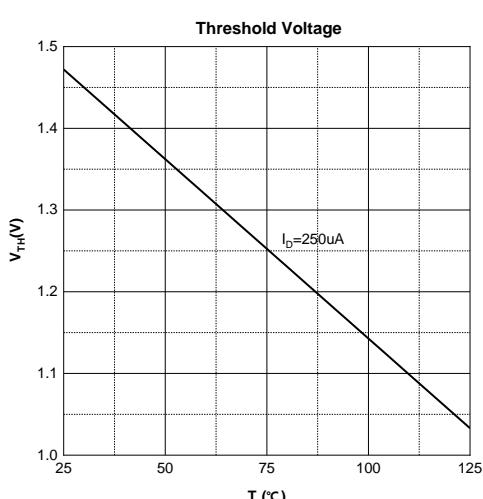
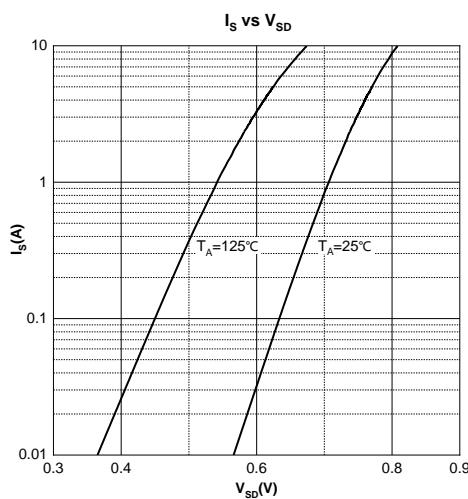
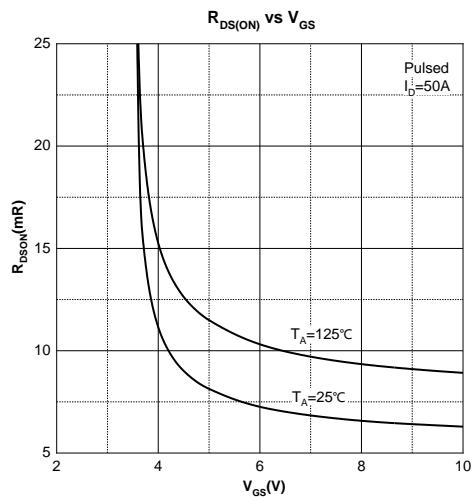
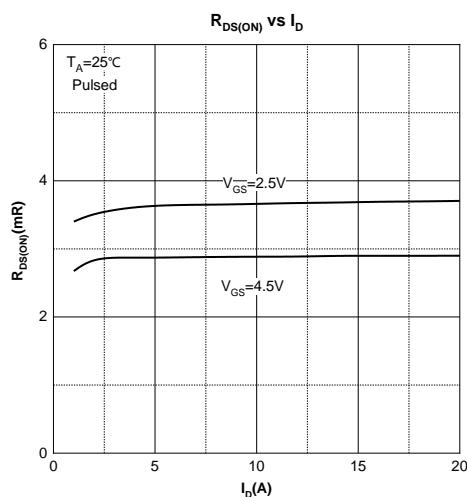
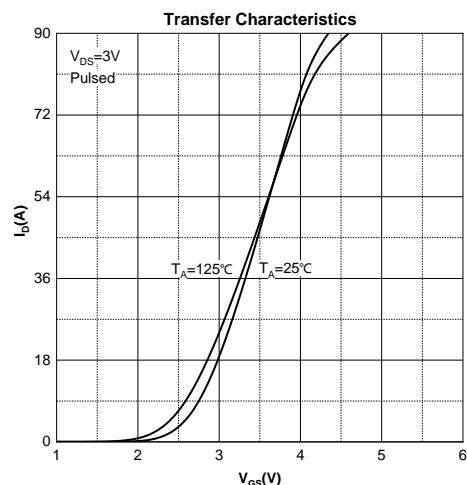
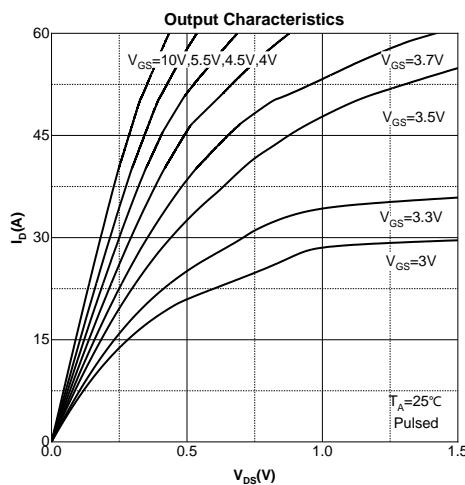
MOSFET ELECTRICAL CHARACTERISTICS($T_A = 25^\circ\text{C}$ unless otherwise noted)

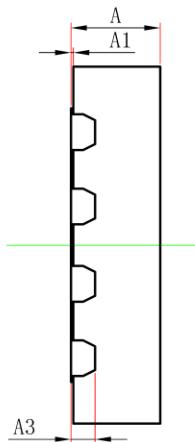
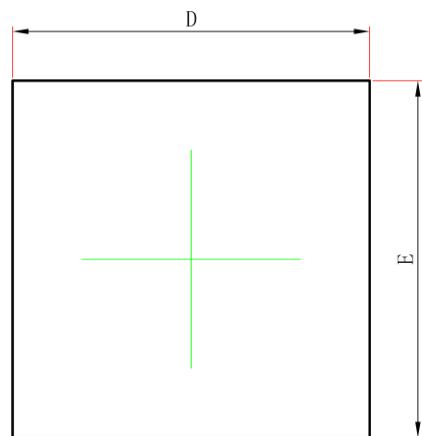
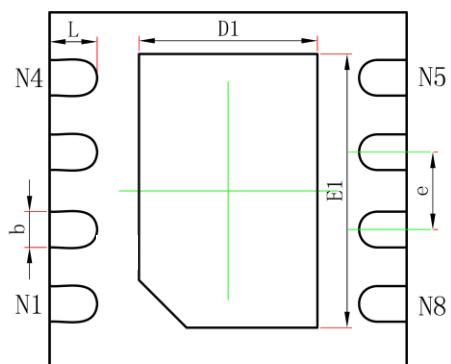
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	12			V
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}} = 12\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
Gate-body leakage current	I_{GSS}	$V_{\text{GS}} = \pm 8\text{V}, V_{\text{DS}} = 0\text{V}$			± 2	μA
On Characteristics³						
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	0.4	0.65	1	V
Drainsource onresistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 4.5\text{V}, I_D = 3\text{A}$		3.1	4.5	$\text{m}\Omega$
		$V_{\text{GS}} = 4\text{V}, I_D = 3\text{A}$		3.2	4.8	
		$V_{\text{GS}} = 3.8\text{V}, I_D = 3\text{A}$		3.3	5	
		$V_{\text{GS}} = 3.1\text{V}, I_D = 3\text{A}$		3.5	5.3	
		$V_{\text{GS}} = 2.5\text{V}, I_D = 3\text{A}$		3.9	5.5	
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 6\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		2092		pF
Output Capacitance	C_{oss}			341		
Reverse Transfer Capacitance	C_{rss}			25		
Gate resistance	R_g	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		3420		Ω
Switching Characteristics						
Total Gate Charge	Q_g	$V_{\text{DS}} = 10\text{V}, V_{\text{GS}} = 4.5\text{V}, I_D = 3\text{A}$		30		nC
GateSource Charge	Q_{gs}			2.3		
GateDrain Charge	Q_{gd}			7.5		
Turnon delay time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 10\text{V}, R_G = 3\Omega, V_{\text{GS}} = 5\text{V}, R_L = 1.35\Omega$		4.4		ns
Turnon rise time	t_r			8.7		
Turnoff delay time	$t_{\text{d}(\text{off})}$			80		
Turnoff fall time	t_f			23		
Diode Characteristics						
Diode Forward Voltage ³	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_s = 1\text{A}$			1.2	V

Notes :

- 1.The maximum current rating is limited by package.
- 2.Pulse Test : Pulse Width $\leq 10\mu\text{s}$, duty cycle $\leq 1\%$.
- 3.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- 4.The power dissipation P_D is limited by $T_{\text{J}(\text{MAX})} = 150^\circ\text{C}$.
- 5.Device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

Typical Characteristics



DFN3x3-8L Package Information

TOP VIEW
SIDE VIEW

BOTTOM VIEW

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A3	0.203REF		0.008REF	
D	2.900	3.100	0.114	0.122
E	2.900	3.100	0.114	0.122
D1	1.450	1.650	0.057	0.065
E1	2.250	2.550	0.089	0.100
b	0.250	0.350	0.010	0.014
e	0.650BSC		0.026BSC	
L	0.300	0.500	0.012	0.020